

AMENDMENTS TO THE CLAIMS

Please amend the claims of the present application as set forth below

1. - 42. (Cancelled).

43. (Previously Presented) A method of forming slots in a semiconductor substrate having first and second opposing surfaces comprising:

making a cut into a first surface of a semiconductor substrate using a cutting tool, wherein the cutting tool has an axis of rotation that is not perpendicular to the first surface; and,

removing material from a second surface of the semiconductor substrate effective to form, in combination with said cut, a slot at least a portion of which passes entirely through the substrate, the slot being defined, at least in part, by first and second sidewalls and first and second endwalls extending therebetween, and wherein said making forms a first portion of the end walls and said removing forms a second portion of the end walls and wherein the first and second portions of each of the end walls meet at angle greater than or equal to ninety degrees relative to the substrate.

44. (Cancelled)

45. (Cancelled)

46. (New) The method of claim 43, wherein the cutting tool comprises a circular saw.

47. (New) The method of claim 46, wherein the act of making a cut comprises making multiple cuts into the first surface with the circular saw.

48. (New) The method of claim 43, wherein said removing comprises one or more of: sand drilling, dry etching, wet etching, and drilling with a rotary drill bit.